

Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

## **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

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PCN #: Product Affe	F0305-05 cted: IDT82V3001F	DATE: PV, IDT82V3	5/31/2003 002PV	<ul> <li>MEANS OF DISTINGUISHING CHANGED DEVICES:</li> <li>Product Mark</li> <li>Back Mark</li> <li>Date Code</li> </ul>			
Date Effectiv	ve: 8/31/2003			□ Other			
Contact:	Dasharath Patel						
Title:	Quality Assurance Ma	nager		Attachment:: Yes No			
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E-mail:	Dasharath.Patel@idt.c	<u>om</u>					
<ul> <li>Die Techr</li> <li>Wafer Fah</li> <li>Assembly</li> <li>Equipmen</li> <li>Material</li> <li>Testing</li> <li>Manufacti</li> <li>Data Shee</li> <li>Other</li> </ul> <b>RELIABILI RELIABILI</b> IDT records to grant apprit will be ass IDT reserves	rication Process Process at uring Site at TY/QUALIFICATION R ACKNOWLEDGMI indicate that you requir roval or request addition umed that this change is	N SUMMAR ENT OF REC e written notifial information s acceptable. version manu	Product enhar as described in IDT82V30011 IDT82V30021 Y: Please see CEIPT: fication of this c h. If IDT does n	cement to address the current errata for "Lock" pin a the attachment. PV mark will change to IDT82V3001APV PV mark will change to IDT82V3002APV attachment for qualification summary hange. Please use the acknowledgement below or E-Mail of receive acknowledgement within 30 days of this notice e process change effective date until the inventory			
~							
Customer:			- 🗆	Approval for shipments prior to effective date.			
Name/Date:			E-]	Mail Address:			
Title:			Ph	Phone# /Fax# :			
CUSTOME	R COMMENTS:						
IDT ACKNO	OWLEDGMENT OF I	RECEIPT:					
RECD. BY:				DATE:			



**Test Vehicle:** 

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## ATTACHMENT - PCN # F0305-05

Qualification Plan: QFI-01-16

Test Description/Condition	Test Methods	SS /# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	77/0	77/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

82V3002

Characterization Data:

Characterization Data is available upon request.



### ATTACHMENT - PCN # F0305-05

### Conversion note for 82V3001/82V3002 to new "A" version

#### 1.) Top Mark

The top mark will change as follows82V3001PVwill change to82V3082V3002PVwill change to82V30

82V3001APV 82V3002APV

#### 2.) The new "A" version offers a fully pin compatible upgrade path

The 82V3001A is fully pin compatible with the 82V3001 The 82V3002A is fully pin compatible with the 82V3002

#### 3.) The current errata dated August 2002 has been fixed in the 3001A/3002A

**Current Errata:** Under certain conditions, the LOCK pin could give a false indication of being locked (logic high pulse) of variable duration less than 1 second. The above described errata has been fixed in the "A" version. For further description of the Lock Indication refer to the data sheet.

#### 4.) Improvement of TIE Enable

In the current product 82V3001/82V3002, TIE Enable is automatically enabled when the mode is changed from Auto Holdover mode to Normal mode.

The new 82V3001A/82V3002A permits the user to manually enable or disable the TIE control block with the TIE\_en pin. When TIE\_en is high, the A part acts like the non-A part.

#### 5.) BSDL Files

New BSDL files are available for the 82V3001A/82V3002A and can be downloaded from IDT's Web Page

#### 6.) JTAG IDs

The JTAG IDs have been changed with the conversion to the "A" version as shown below:

82V3001A:	0x4BC	from	82V3001:	0x41E
82V3002A:	0x4BD	from	82V3002:	0x41F